



## Material Content Data Sheet



<b>Sales Product Name</b>				IPC50N04S5L-5R5		<b>Issued</b>		9. January 2019	
<b>MA#</b>				MA001691482					
<b>Package</b>				PG-TDSON-8-33		<b>Weight*</b>		111.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.293	0.26	0.26	2637	2637	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		143		
	non noble metal	iron	7439-89-6	0.053	0.05		476		
wire	non noble metal	copper	7440-50-8	52.842	47.50	47.56	474966	475585	
	noble metal	gold	7440-57-5	0.046	0.04	0.04	414	414	
encapsulation	organic material	carbon black	1333-86-4	0.077	0.07		694		
	plastics	epoxy resin	-	6.098	5.48		54811		
leadfinish	inorganic material	silicondioxide	60676-86-0	32.419	29.14	34.69	291399	346904	
	non noble metal	tin	7440-31-5	1.574	1.41	1.41	14146	14146	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1881	1881	
solder	non noble metal	tin	7440-31-5	0.009	0.01		84		
	noble metal	silver	7440-22-4	0.012	0.01		105		
heatspreader	non noble metal	lead	7439-92-1	0.446	0.40	0.42	4009	4198	
	inorganic material	phosphorus	7723-14-0	0.000	0.00		1		
heat sink CLIP	non noble metal	iron	7439-89-6	0.000	0.00		3		
	non noble metal	copper	7440-50-8	0.310	0.28	0.28	2782	2786	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		151		
*deviation	non noble metal	copper	7440-50-8	16.828	15.13	15.15	151253	151449	
						Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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